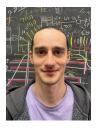
Nanofabricated bolometers with ribbon resonators





Ilya Golokolenov (Basel/Grenoble), Eddy Collin (Grenoble), **Lev Levitin**, Andrew Casey (Royal Holloway) Elizabeth Leason (Oxford), Dmitri Zmeev (Lancaster)

QUEST DMC meeting, Liverpool, 17 October 2025

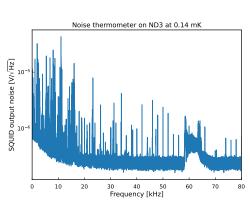
Motivation

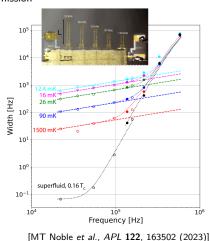
Large cross section-to-mass ratio: strong coupling to quasiparticles

Scalability for arrays of small ($\sim 1\,\mathrm{mm}^3$) bolometers

Well-defined frequencies and vibrational modes

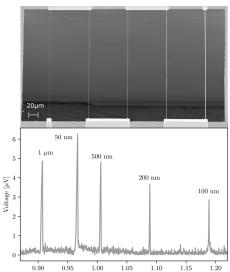
10-100 kHz range: no fridge vibrations, no acoustic emission





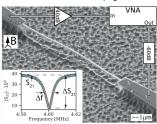
Nanofabricated mechanical resonators for superfluids

Grenoble: $100\,\text{nm}$ strained $\text{Si}_3\,\text{N}_4\,+\,30\,\text{nm}$ Al



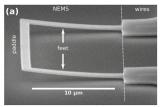
[I Golokolenov et al., JLTP 210, 550 (2023)]

Lancaster: $100 \,\mathrm{nm}$ AI, $f_0 = 0.6-8 \,\mathrm{MHz}$



[MT Noble et al., APL 125, 073502 (2024)]

Helsinki: 150 nm Al, $f_0 = 0.4 \,\mathrm{MHz}$

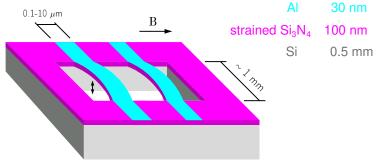


[T Kamppinen and VB Eltsov, JLTP, 196, 283 (2019)]

Frequency [MHz]

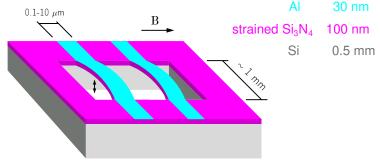
Ribbon resonators

Proposal: Grenoble beams with increased width



Ribbon resonators

Proposal: Grenoble beams with increased width



Sharp corners: small critical velocity?

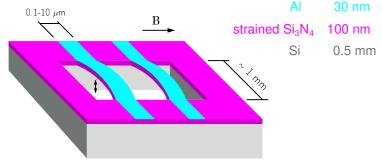


[side view]

Maybe not: [T Kamppinen and V Elstov, unpublished]

Ribbon resonators

Proposal: Grenoble beams with increased width

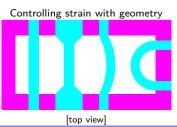




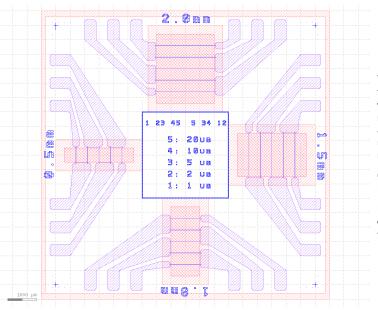


[side view]

Maybe not: [T Kamppinen and V Elstov, unpublished]



Ribbon resonators: work in progress at Institut Néel, CNRS, Grenoble



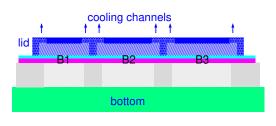
Tests:

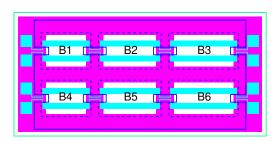
reguencies and widths in vacuum, response to helium, acoustic emission, reproducibility and reliability.

Other designs: Bent ribbons

Narrow ribbons to explore decoupling from superfluid ³He

Nanofabricated bolometers





Superfluid devices with stepped confinement: [P Heikkinen *et al.*, *JLTP* **215**, 477 (2024)]

Precise bolometer volumes and cooling channels.

Assembly in cleanroom. Protection of ribbons from dust and damage.

Challenge: need to bond 3 wafers, but leaktight bond not required. May use individual lids and bottoms. [X Rojas and JP Davis, *PRB* **91** (2015)]

Electrical leads in the cooling channels

Multiplexing: offset resonances i.e. by varying ribbon lengths. High reliability is essential.

